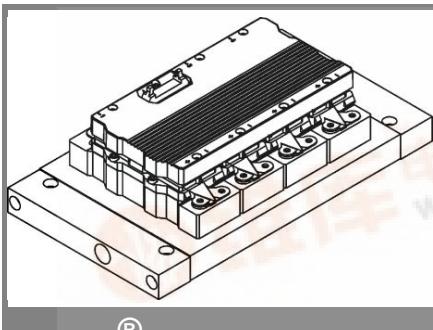


SKIIP 2403GB172-4DW



SKiIP® 3

2-pack-integrated intelligent Power System

Power section

SKIIP 2403GB172-4DW

Preliminary Data

Features

- SKiIP technology inside
- Trench IGBTs
- CAL diode technology
- Integrated current sensor
- Integrated temperature sensor
- Integrated heat sink
- IEC 60721-3-3 (humidity) class 3K3/IE32 (SKiIP® 3 System)
- IEC 60068-1 (climate) 40/125/56
- UL recognized file no. E63532

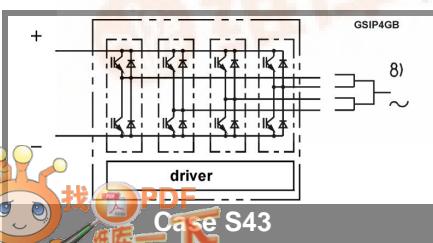
1) with assembly of suitable MKP capacitor per terminal (SEMIKRON type is recommended)

8) AC connection busbars must be connected by the user; copper busbars available on request

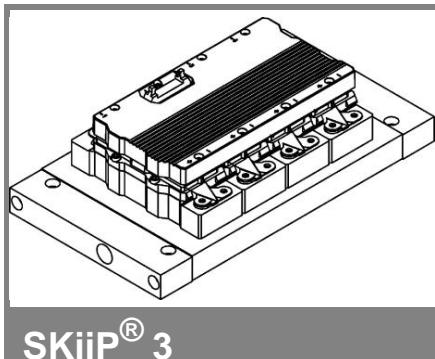
Absolute Maximum Ratings		$T_s = 25^\circ\text{C}$ unless otherwise specified		
Symbol	Conditions	Values		Units
IGBT				
V_{CES}		1700		V
V_{CC} ¹⁾	Operating DC link voltage	1200		V
V_{GES}		± 20		V
I_C	$T_s = 25 \text{ (70)}^\circ\text{C}$	2400 (1800)		A
Inverse diode				
$I_F = -I_C$	$T_s = 25 \text{ (70)}^\circ\text{C}$	1800 (1400)		A
I_{FSM}	$T_j = 150^\circ\text{C}$, $t_p = 10 \text{ ms}$; sin.	13500		A
I^t (Diode)	Diode, $T_j = 150^\circ\text{C}$, 10 ms	911		kA ² s
T_j (T_{stg})		- 40 ... + 150 (125)		°C
V_{isol}	rms, AC, 1 min, main terminals to heat sink	4000		V
$I_{AC-terminal}$	per AC terminal, rms, $T_s = 70^\circ\text{C}$,	400		A
	$T_{terminal} < 115^\circ\text{C}$			

Characteristics		$T_s = 25^\circ\text{C}$ unless otherwise specified		
Symbol	Conditions	min.	typ.	max.
IGBT				
V_{CEsat}	$I_C = 1200 \text{ A}$, $T_j = 25 \text{ (125)}^\circ\text{C}$; measured at terminal	1,9 (2,2)	2,4	V
V_{CEO}	$T_j = 25 \text{ (125)}^\circ\text{C}$; at terminal	1 (0,9)	1,2 (1,1)	V
r_{CE}	$T_j = 25 \text{ (125)}^\circ\text{C}$; at terminal	0,8 (1)	1 (1,3)	mΩ
I_{CES}	$V_{GE} = 0 \text{ V}$, $V_{CE} = V_{CES}$, $T_j = 25 \text{ (125)}^\circ\text{C}$	4,8 (288)		mA
$E_{on} + E_{off}$	$I_C = 1200 \text{ A}$, $V_{CC} = 900 \text{ V}$	780		mJ
	$T_j = 125^\circ\text{C}$, $V_{CC} = 1200 \text{ V}$	1150		mJ
$R_{CC+EE'}$	terminal chip, $T_j = 25^\circ\text{C}$	0,13		mΩ
L_{CE}	top, bottom	3		nH
C_{CHC}	per phase, AC-side	4		nF
Inverse diode				
$V_F = V_{EC}$	$I_F = 1200 \text{ A}$, $T_j = 25 \text{ (125)}^\circ\text{C}$ measured at terminal	2 (1,8)	2,15	V
V_{TO}	$T_j = 25 \text{ (125)}^\circ\text{C}$	1,1 (0,8)	1,2 (0,9)	V
r_T	$T_j = 25 \text{ (125)}^\circ\text{C}$	0,8 (0,8)	0,8 (0,9)	mΩ
E_{rr}	$I_C = 1200 \text{ A}$, $V_{CC} = 900 \text{ V}$	144		mJ
	$T_j = 125^\circ\text{C}$, $V_{CC} = 1200 \text{ V}$	171		mJ
Mechanical data				
M_{dc}	DC terminals, SI Units	6	8	Nm
M_{ac}	AC terminals, SI Units	13	15	Nm
w	SKiIP® 3 System w/o heat sink	3,1		kg
w	heat sink	6,2		kg
Thermal characteristics (NWK 40; 8l/min; 50%glyc.) ; "s" reference to heat sink; "r" reference to built-in temperature sensor (acc. IEC 60747-15)				
$R_{th(j-s)l}$	per IGBT		0,013	K/W
$R_{th(j-s)D}$	per diode		0,025	K/W
Z_{th}	R_i (mK/W) (max. values)		$\tau_{th}(s)$	
	1 2 3 4	1	2	3 4
$Z_{th(j-r)l}$	1,2 5 5,8 0	69	0,35	0,02 1
$Z_{th(j-r)D}$	2 3 13,5 13,5	50	5	0,25 0,04
$Z_{th(r-a)}$	2,7 4,6 1,1 0,6	48	15	2,8 0,4

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SKiiP 2403GB172-4DW



2-pack-integrated intelligent Power System

2-pack integrated gate driver SKiiP 2403GB172-4DW

Preliminary Data

Gate driver features

- CMOS compatible inputs
- Wide range power supply
- Integrated circuitry to sense phase current, heat sink temperature and DC-bus voltage (option)
- Short circuit protection
- Over current protection
- Over voltage protection (option)
- Power supply protected against under voltage
- Interlock of top/bottom switch
- Isolation by transformers
- Fibre optic interface (option for GB-types only)
- IEC 60068-1 (climate) 40/85/56
- UL recognized file no. 242581

Absolute Maximum Ratings		$T_a = 25^\circ\text{C}$ unless otherwise specified	
Symbol	Conditions	Values	Units
V_{S2}	unstabilized 24 V power supply	30	V
V_i	input signal voltage (high)	15 + 0,3	V
$\frac{dv}{dt}$	secondary to primary side	75	$\text{kV}/\mu\text{s}$
V_{isolIO}	input / output (AC, rms, 2s)	4000	V
V_{isolPD}	partial discharge extinction voltage, rms, $Q_{\text{PD}} \leq 10 \text{ pC}$	1500	V
V_{isol12}	output 1 / output 2 (AC, rms, 2s)	1500	V
f_{sw}	switching frequency	7	kHz
f_{out}	output frequency for $I=I_c$; sin.	1	kHz
$T_{\text{op}} (T_{\text{stg}})$	operating / storage temperature	- 40 ... + 85	$^\circ\text{C}$

Characteristics $(T_a = 25^\circ\text{C})$				
Symbol	Conditions	min.	typ.	max.
V_{S2}	supply voltage non stabilized	13	24	30
I_{S2}	$V_{S2} = 24 \text{ V}$	$430+45*f/\text{kHz}+0,00011*(I_{AC}/A)^2$		
V_{IT+}	input threshold voltage (High)	12,3		
V_{IT-}	input threshold voltage (Low)	4,6		
R_{IN}	input resistance	10		
C_{IN}	input capacitance	1		
$t_{d(on)}^{\text{IO}}$	input-output turn-on propagation time	1,3		
$t_{d(off)}^{\text{IO}}$	input-output turn-off propagation time	1,3		
$t_{\text{pERRRESET}}$	error memory reset time	9		
t_{TD}	top / bottom switch interlock time	3,3		
$I_{\text{analogOUT}}$	max. 5mA; 8 V corresponds to 15 V supply voltage for external components	2000		
I_{s1out}	max. load current	50		
I_{TRIPSC}	over current trip level ($I_{\text{analog OUT}} = 10 \text{ V}$)	2500		
T_{tp}	over temperature protection	110	120	
U_{DCTRIP}	$U_{\text{DC}}\text{-protection } (U_{\text{analog OUT}} = 9 \text{ V})$; (option for GB types)	not implemented		

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